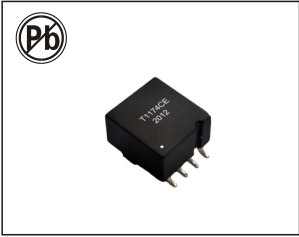


BROADBAND PLC TRANSFORMER

T1174CE

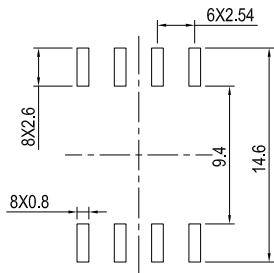
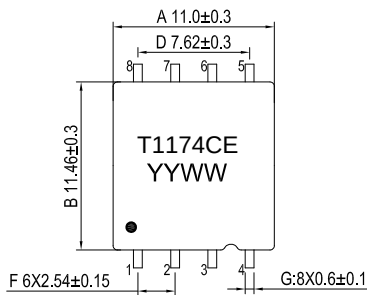
FEATURES:

- DESIGN FOR PLC(POWER LINE COMMUNICATION) APPLICATION.
- ROHS COMPLIANT.
- REINFORCED INSULATION
- OPERATING TEMPERATURE RANGE: -40℃ TO 85℃.

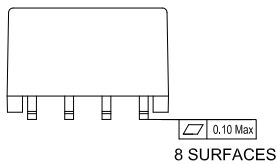
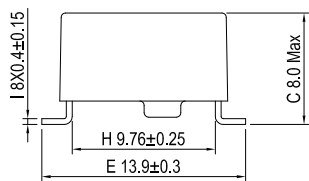


Electrical Specifications @25°C								
Part Number	Turns Ratio (100KHz,1V)	OCL (100KHz,0.1V)	LL (100KHz,0.1V)	Cww (100KHz,0.1V)	DCR	Insertion loss @2-80MHz	Return loss @2-80MHz	Hi-Pot
T1174CE	8-1:2-7:3-6:4-5	8-1,2-7,3-6,4-5	8-1 (tie2-7,3-6,4-5)	1-2 (tie7+3,6+4)	8-1,2-7,3-6,4-5	8-1 To 2-7,3-6,4-5	8-1 To 2-7,3-6,4-5	Pri TO Sec
	1:1:1:1±2%	300uH Min	0.6uH Max	25pF Max	0.5Ω Max	-1.4dB Max	-15dB Min	1500VAC 1.0mA,60S

MECHANICAL DIMENSIONS(unit:mm)

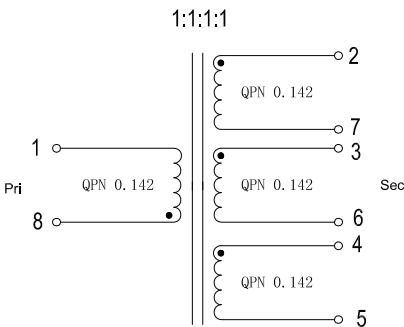


SUGGESTED PAD LAYOUT



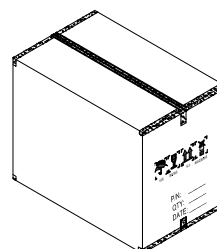
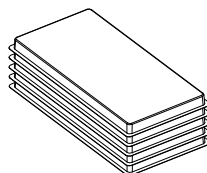
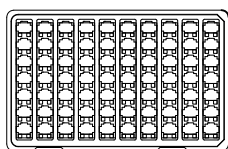
● Unless otherwise specified all tolerances are:±0.25 mm

SCHEMATICS



PACKING:

☐ Tray:

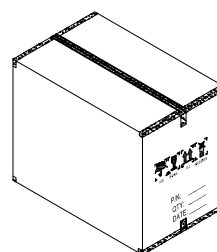
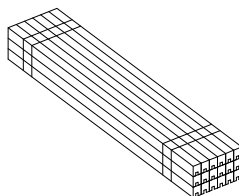


Q'ty

_____ PCS Per Tray

_____ PCS Per Carton

☐ Tube:

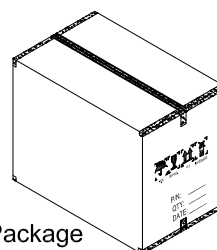
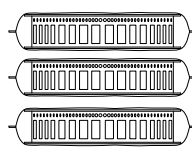
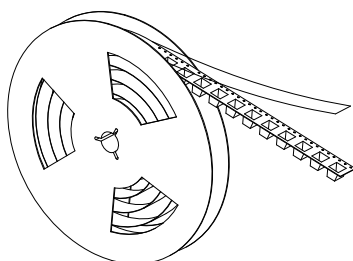


Q'ty

_____ PCS Per Tube

_____ PCS Per Carton

☒ Reel:



Vacuumize Package

Q'ty

400 PCS Per Reel

2800 PCS Per Carton

MOISTURE SENSITIVE LEVEL:

1. Level:1
- 2.Shelf Life:Unlimited
- 3.Storage Condition:≤30℃/85% RH

RECOMMENDED SOLDERING PROFILE:

☒ 1. Reflow soldering profile(According to IPC/JEDEC J-STD-020C)

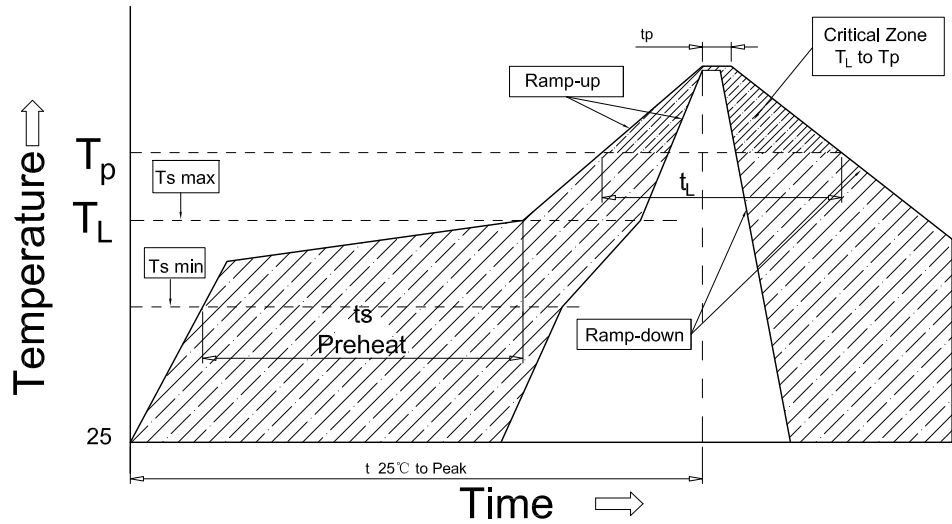


Table 1-1 Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T _{smax} to T _p)	3°C/second max	3°C/second max
Preheat		
-Temperature Min (T _{smin})	100°C	150°C
-Temperature Max (T _{smax})	150°C	200°C
-Time (t _{smin} to t _{smax})	60-120 seconds	60-180 seconds
Time maintained above:	183°C	217°C
-Temperature (T _l)	60-150 seconds	60-150 seconds
-Time (t _l)		
Peak/Classification Temperature(T _p)	See IPC/JEDEC J-STD-020C Table 4-1	See IPC/JEDEC J-STD-020C Table 4-2
Time within 5°C of actual Peak Temperature(tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max	8 minutes max

Note1: All temperatures refer to topside of the package, measured on the package body surface

- Suggested soldering process: Reflow soldering
Solder Paste: Sn96.5Ag3.0Cu0.5
Silkscreen thickness: 0.15mm Min.

☐ 2. Wave soldering profile

